

Claims

- [c1] 1. A bumping process, comprising:
- providing a wafer having a plurality of bonding pads and a passivation layer that exposes the bonding pads;
- forming a metallic layer over the wafer to cover at least the bonding pads;
- forming a first photoresist layer over the wafer;
- forming a second photoresist layer over the first photoresist layer, wherein the first photoresist layer has a viscosity smaller than the second photoresist layer;
- performing an exposure and development process to form a plurality of openings in the first and the second photoresist layer, wherein the openings expose the metallic layer;
- filling a solder material into the openings to form a plurality of solder posts; and
- removing the first photoresist layer and the second photoresist layer.
- [c2] 2. The bumping process of claim 1, further comprising performing a reflow process to transform the solder posts into a plurality of bumps over the metallic layer after removing the first and the second photoresist layer.

- [c3] 3. The bumping process of claim 1, wherein the first photoresist layer comprises a dry film.
- [c4] 4. The bumping process of claim 1, wherein the second photoresist layer comprises a dry film.
- [c5] 5. The bumping process of claim 1, wherein the step of filling the solder material into the openings comprises electroplating or stencil printing.
- [c6] 6. A method for enhancing the adhesion between a photoresist material and a substrate, comprising:
forming a first photoresist layer over the substrate; and
forming a second photoresist layer over the first photoresist layer, wherein the second photoresist layer has a higher viscosity than the first photoresist layer.
- [c7] 7. The method of claim 6, wherein the first photoresist layer comprises a dry film.
- [c8] 8. The method of claim 6, wherein the second photoresist layer comprises a dry film.